

Appl. No. 10/727,740
Reply to Office action of 01/05/2005

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-17 (Canceled).

18. (Currently amended) A fabrication method, comprising the steps of:
varying the history of wafers within a lot by transporting individual ones wafers thereof within a processing tool with multiple processing chambers, among said chambers and wafer cassette and/or staging locations in various different sequences.
19. (Original) The method of Claim 18, further comprising the contemporaneous step of recording process sequence data for said wafers.
20. (Original) The method of Claim 18, further comprising the subsequent step of correlating fault and/or parametric data with process sequence data resulting from said varying step.
21. (Original) The method of Claim 18, further comprising the subsequent step of correlating fault and/or parametric data with process sequence data resulting from said varying step, and controlling process parameters accordingly.
- 22-26. (Cancelled).
27. (new) The method of claim 18, wherein said chambers are randomly selected during said varying step.